



HS

**DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: **Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, And Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit**, Serial No. 09/449,025, filed November 24, 1999.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

**PRIOR FOREIGN APPLICATIONS:**

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

1 Section 1001 of Title 18 of the United States Code and that such willful  
2 false statement may jeopardize the validity of the application or any  
3 patent issued therefrom.

4 \* \* \* \* \*

5 Full name of inventor: **Shozo Nagano**

6 Inventor's Signature: \_\_\_\_\_

7 Date: \_\_\_\_\_

8 Residence: **Kanagawa, Japan**

9 Citizenship: **Japanese**

10 Post Office Address: **1-3-5-405 Mizuhiki Atsugi**  
**Kanagawa, Japan 234-004**

11 \* \* \* \* \*

12  
13 Full name of inventor: **Hinrich Hargarter**

14 Inventor's Signature: \_\_\_\_\_

15 Date: \_\_\_\_\_

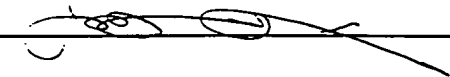
16 Residence: **The Netherlands**

17 Citizenship: **German**

18 Post Office Address: **P.O. Box 10000**  
**1970 CA IJmuiden**  
19 **The Netherlands**

\* \* \* \* \*

Full name of inventor: **Jianxing Li**

Inventor's Signature: 

Date: 4/27/00

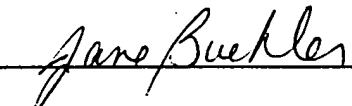
Residence: **Spokane, Washington**

Citizenship: **Chinese**

Post Office Address: **4908 N. Calvin Road  
Spokane, WA 99216**

\* \* \* \* \*

Full name of inventor: **Jane Buehler**

Inventor's Signature: 

Date: 04/27/00

Residence: **Spokane, Washington**

Citizenship: **U.S.**

Post Office Address: **18517 E. Norman Ridge Lane  
Spokane, WA 99217**



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4 \* \* \* \* \*

5 Full name of inventor: Shozo Nagano

6 Inventor's Signature: Shozo Nagano

7 Date: 2/1/2000

8 Residence: Kanagawa, Japan

9 Citizenship: Japanese

10 Post Office Address: 1-3-5-405 Mizuhiki Atsugi  
11 Kanagawa, ~~Japan 234-004~~  
243-0004 Japan

12 \* \* \* \* \*

13 Full name of inventor: Hinrich Hargarter

14 Inventor's Signature: \_\_\_\_\_

15 Date: \_\_\_\_\_

16 Residence: The Netherlands

17 Citizenship: German

18 Post Office Address: P.O. Box 10000  
19 1970 CA IJmuiden  
The Netherlands

\* \* \* \* \*

Full name of inventor: Jianxing Li

Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: Spokane, Washington

Citizenship: Chinese

Post Office Address: 4908 N. Calvin Road  
Spokane, WA 99216

\* \* \* \* \*

Full name of inventor: Jane Buehler

Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: Spokane, Washington

Citizenship: U.S.

Post Office Address: 18517 E. Norman Ridge Lane  
Spokane, WA 99217



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14 Inventor's Signature: Hinrich Hargarter

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18 Post Office Address: P.O. Box 10000  
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Full name of inventor: **Jane Buehler**

Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

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